

Application Note

Replacing TIOL111x with CCE4503

AN-IO-001

Abstract

This document contains all changes that might be necessary to replace the TIOL111x with the CCE4503.

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References

- [1] CCE4503, Datasheet, Dialog Semiconductor.
- [2] TIOL111x, Datasheet, Texas Instruments.

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1 Package size

The package size of the CCE4503 and the TIOL111x is slightly different (see Figure 1).

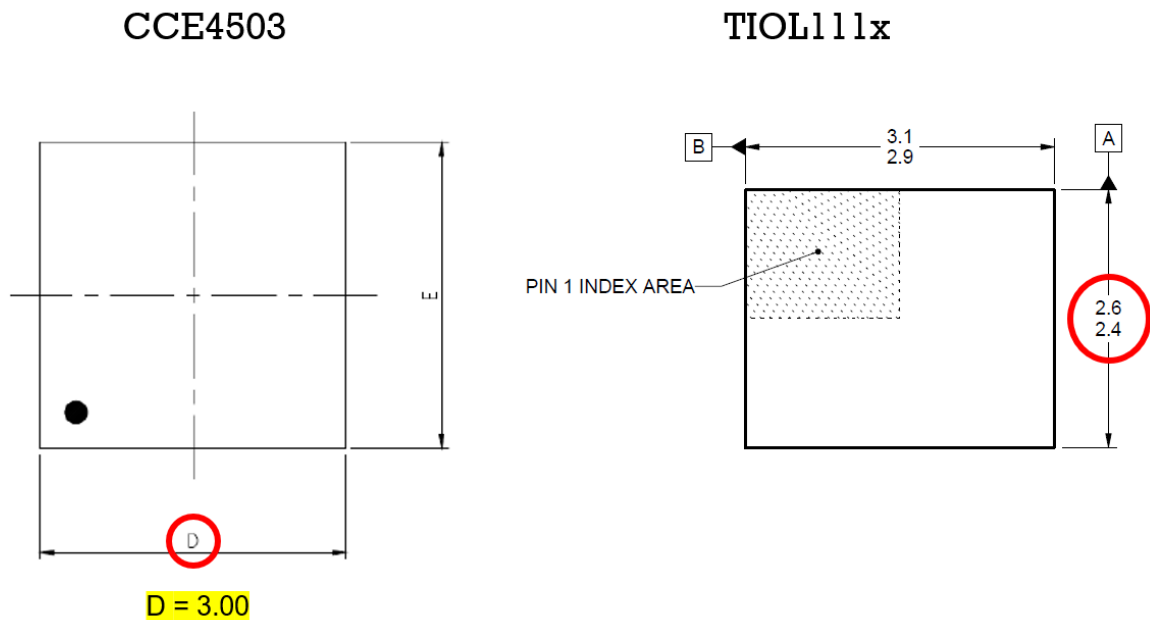


Figure 1: Package size comparison (in mm)

The CCE4503 has a package size of 3 mm x 3 mm while the TIOL111x (see References [2]) has a package size of 3 mm x 2.5 mm. This difference needs to be considered regarding the PCB layout. This does not affect the pitch between the pins.

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2 Footprint change

Since the footprint of the TIOL111x and the CCE4503 have slightly differences it might be necessary to adapt the footprint on the PCB.

The difference is shown in the following figure.

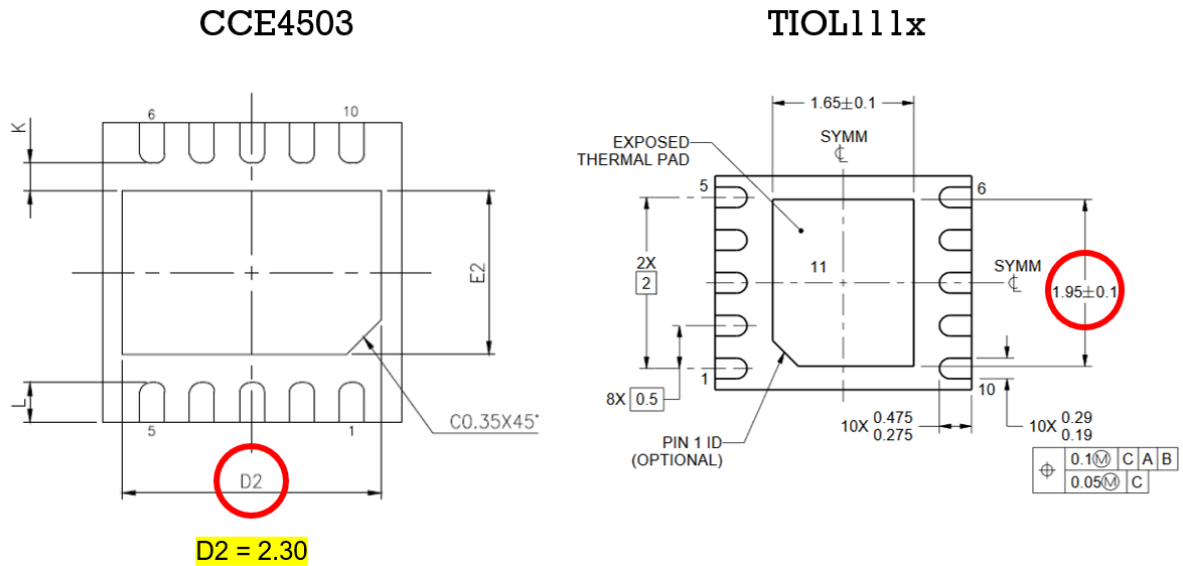


Figure 2: Footprint comparison (in mm)

The CCE4503 has an exposed pad length of 2.30 mm while the TIOL111x (see References [2]) has an exposed pad length of 1.95 mm. This difference needs to be considered regarding the PCB layout.

Replacing TIOL111x with CCE4503**Revision History**

Revision	Date	Description
2	10-Dec-2020	Added package size comparison
1	01-Dec-2020	Initial version.

Replacing TIOL111x with CCE4503

Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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Contacting Dialog Semiconductor

United Kingdom (Headquarters)

Dialog Semiconductor (UK) LTD
Phone: +44 1793 757700

Germany

Dialog Semiconductor Bingen GmbH
Phone: +49 6721 987 22 0

The Netherlands

Dialog Semiconductor B.V.
Phone: +31 73 640 8822

Email:

enquiry@diasemi.com

North America

Dialog Semiconductor Inc.
Phone: +1 408 845 8500

Japan

Dialog Semiconductor K. K.
Phone: +81 3 5769 5100

Taiwan

Dialog Semiconductor Taiwan
Phone: +886 281 786 222

Web site:

www.dialog-semiconductor.com

Hong Kong

Dialog Semiconductor Hong Kong
Phone: +852 2607 4271

Korea

Dialog Semiconductor Korea
Phone: +82 2 3469 8200

China (Shenzhen)

Dialog Semiconductor China
Phone: +86 755 2981 3669

China (Shanghai)

Dialog Semiconductor China
Phone: +86 21 5424 9058